L	Hits	Search Text	DB	Time stamp
Number				_
8	187	<pre>cod\$3 and (label\$3 or tag\$3) and (microparticle\$1 or micro-particle) and</pre>	USPAT; US-PGPUB;	2003/07/10 05:53
		wafer\$3 and (silicon or dioxide or metal)	EPO; JPO;	
3	. 8	and optical\$3 ((microparticle\$1 or micro-particle) same wafer\$3) and (silicon or dioxide or	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/07/10 13:40
	4	metal) and optic\$3 and thickness and width\$3 and length\$3	EPO; JPO; DERWENT; IBM_TDB	
4	1	<pre>cod\$3 same (label\$3 or tag\$3) same (microparticle\$1 or micro-particle) same wafer\$3</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10
5	48	<pre>cod\$3 same (label\$3 or tag\$3) same (microparticle\$1 or micro-particle)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 05:54
9	37	<pre>cod\$3 and (label\$3 or tag\$3) and (microparticle\$1 or micro-particle) and wafer\$3 and (silicon or dioxide or metal) and optical\$3 and (pit\$1 or hole\$1 or notch\$3)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 05:54
10	22	(microparticle\$1 or micro-particle) and wafer\$3 and (silicon or dioxide or metal) and cod\$3 and thickness and width\$3 and length\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 10:27
14		<pre>(cod\$3 adj (label\$3 or tag\$2)) same (microparticle\$1 or micro-particle)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 06:31
17	57	<pre>(cod\$3 adj (label\$3 or tag\$2)) and (microparticle\$1 or micro-particle)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/10 06:31
18	. 86	<pre>(cod\$3 adj (label\$3 or tag\$2 or item\$1)) with (microparticle\$1 or micro-particle or micro\$6)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 07:29
19 .	7	((cod\$3 adj (label\$3 or tag\$2 or item\$1)) with (microparticle\$1 or micro-particle or micro\$6)) and wafer\$3 and silicon\$3 and metal\$4 and cod\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10
21	4	((cod\$3 adj (label\$3 or tag\$2 or item\$1)) with (microparticle\$1 or micro-particle or micro\$6)) and wafer\$3 and silicon\$3 and metal\$4 and cod\$3 and die and unique	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 09:19
24.	46	((microparticle\$1 or micro-particle) same compound\$1 same (tag\$1 or label\$1)) and (solid\$1 or powder\$3) and liquid\$1 and gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 10:22
25	101	((microparticle\$1 or micro-particle) same wafer\$3) and (solid\$1 or powder\$3) and liquid\$1 and gas and compound\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/10 13:21